

Loctite® 3563 Epoxy Snap Cure Underfill

Category : Polymer , Adhesive , Thermoset , Epoxy , Epoxy Encapsulant, Unreinforced

Material Notes:

COB/DCA Encapsulants are essential to the reliability of flip chip assemblies because they minimize the thermal mismatch between the flip chip and substrate. Loctite® Underfills and Encapsulants improve assembly operations by providing superior reliability and faster throughput. Improved reliability is achieved through products that have a high Tg, low CTE, high throughput and excellent adhesion. Faster throughput and higher yields are achieved through faster flow characteristics and increased cure speeds. Loctite® 3563 Epoxy Snap Cure Underfill Designed specifically for high volume production of flip chip packaging in consumer electronics applications.

Order this product through the following link:

http://www.lookpolymers.com/polymer_Loctite-3563-EpoxySnap-Cure-Underfill.php

Physical Properties	Metric	English	Comments
Density	1.52 g/cc	0.0549 lb/in³	
Viscosity	8000 cP	8000 cP	Haake cone and plate rheometer @ 5/sec (35mm/2° cone)

Mechanical Properties	Metric	English	Comments
Tensile Modulus	2.76 GPa	400 ksi	

Thermal Properties	Metric	English	Comments
CTE, linear	35.0 µm/m-°C	19.4 µin/in-°F	
	@Temperature 20.0 °C	@Temperature 68.0 °F	
Glass Transition Temp, Tg	130 °C	266 °F	

Processing Properties	Metric	English	Comments
Cure Time	5.00 min	0.0833 hour	
	@Temperature 150 °C	@Temperature 302 °F	
Shelf Life	3.00 Month	3.00 Month	
	@Temperature -40.0 °C	@Temperature -40.0 °F	

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